

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ2040M04
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.2936%
Lead Frame	Cu	7440-50-8	96.852%	58.2157%
	Fe	7439-89-6	2.193%	
	Pb	7439-92-1	0.01%	
	P	7723-14-0	0.072%	
	Zn	7440-66-6	0.138%	
	Ag	7440-22-4	0.735%	
Epoxy1	Silver	7440-22-4	80.00%	0.4282%
	bisphenol-F-	9003-36-5	12.00%	
	1,4-bis(2,3	2425-79-8	6.50%	
	dapsone	80-08-0	1.50%	
Epoxy2	Silver	7440-22-4	80.00%	0.4282%
	bisphenol-F-	9003-36-5	12.00%	
	1,4-bis(2,3	2425-79-8	6.50%	
	dapsone	80-08-0	1.50%	
Wire	copper	7440-50-8	99.99%	0.2528%
	others	/	0.01%	
Mold Compound	Epoxy Resin1	Trade secret	6.80%	38.6827%
	Epoxy Resin2	Trade secret	4.70%	
	Phenol Resin	Trade secret	5.30%	
	Carbon Black	1333-86-4	0.20%	
	Amorphous silica	60676-86-0	83.00%	
Plating	Tin	7440-31-5	100.00%	1.6988%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.